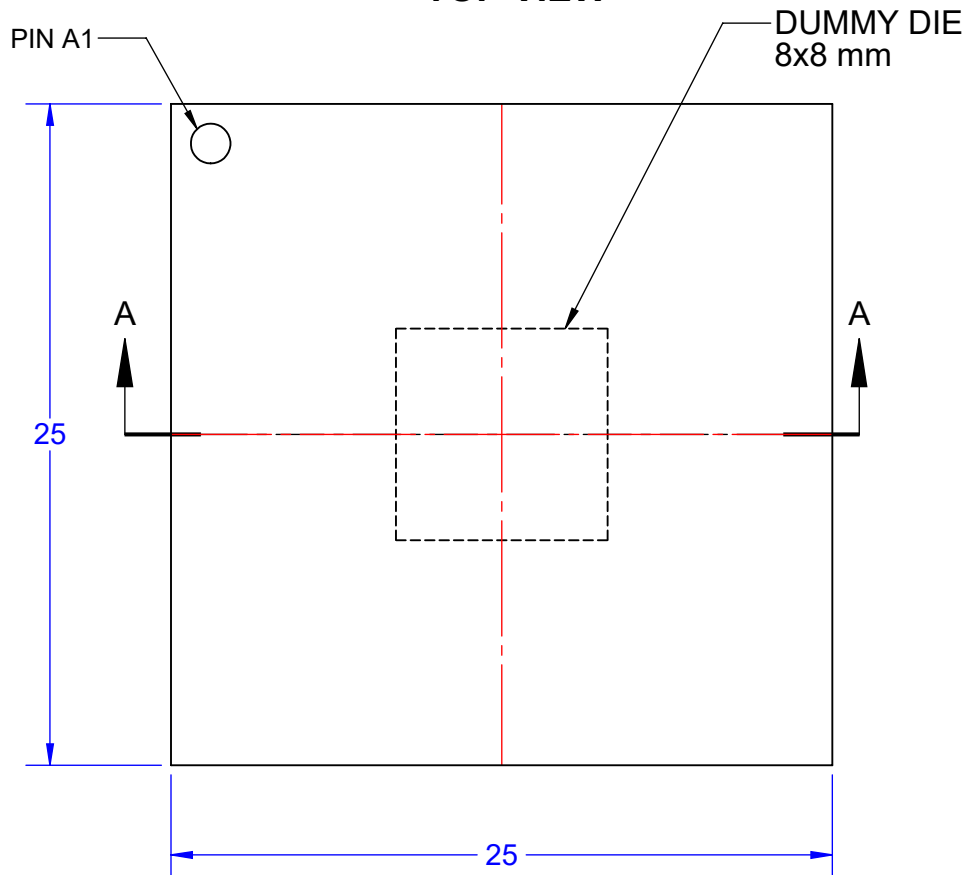
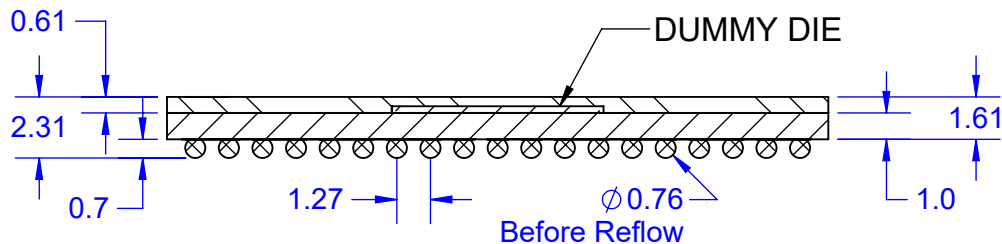
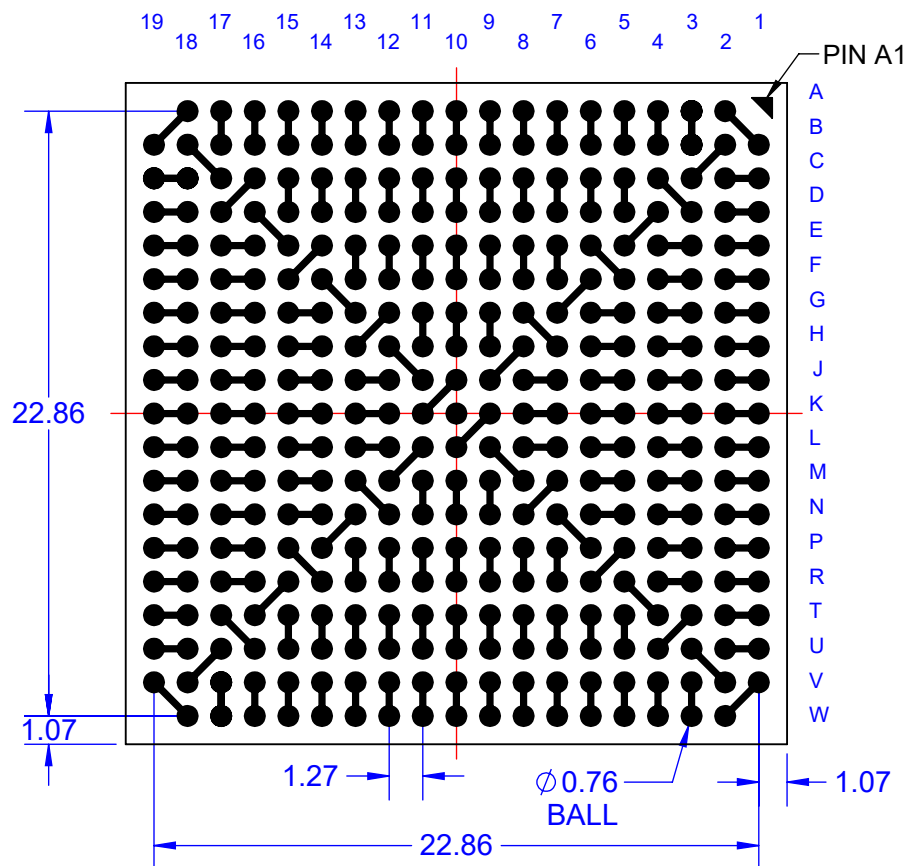


TOP VIEW



BALL VIEW



SECTION A-A
SCALE 3.5 : 1

PART NUMBER TABLE

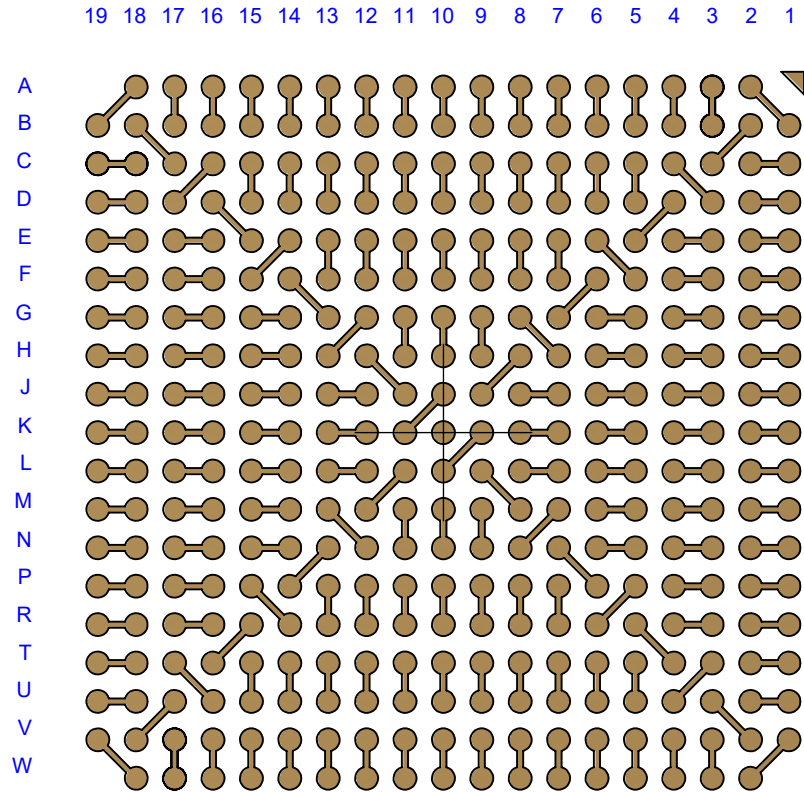
PART NUMBER	BALL ALLOY	BALL CODE	RoHS	Si DIE
BGA357T1.27C-DC73D	Sn96.5/Ag3.0/Cu0.5	SAC305	YES	YES
BGA357T1.27-DC73D	Sn63/Pb37	Sn63	NO	YES

Notes: (Unless Otherwise Specified).

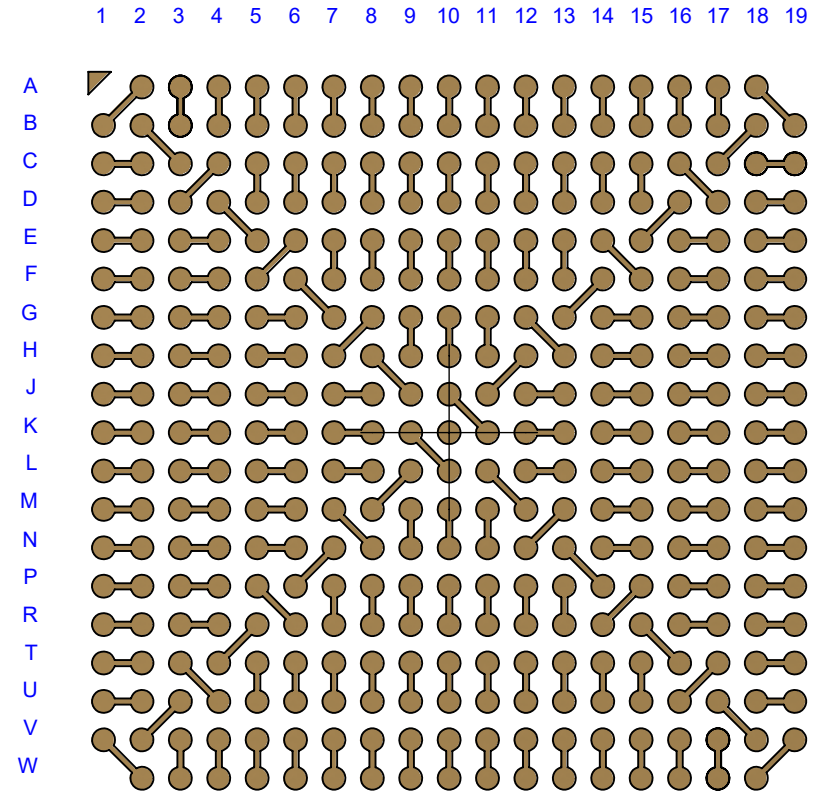
- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.76mm (30 MIL).
- 4) SOLDER MASK DEFINED PAD SRO: 0.61mm (24 MIL).
- 5) PAD Cu DIAMETER: 0.76mm (30 MIL).
- 6) SUBSTRATE MATERIAL: BT.
- 7) DUMMY DIE IS OPTIONAL.
- 8) BALL PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR SOLDERING TO PC BOARD.

APPROVALS	DATE	TopLine®			
DRAWN T.Au	4/14/2022				
ENG M. Hart	4/14/2022	TITLE		BGA357T1.27-DC73D DAISY CHAIN	
MFG		SCALE	SIZE	DRAWING NO.	REV
QA		3.5:1	A	521903	A
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 4
REVISED					

BALL VIEW



BOTTOM SIDE (TOP X-RAY VIEW)



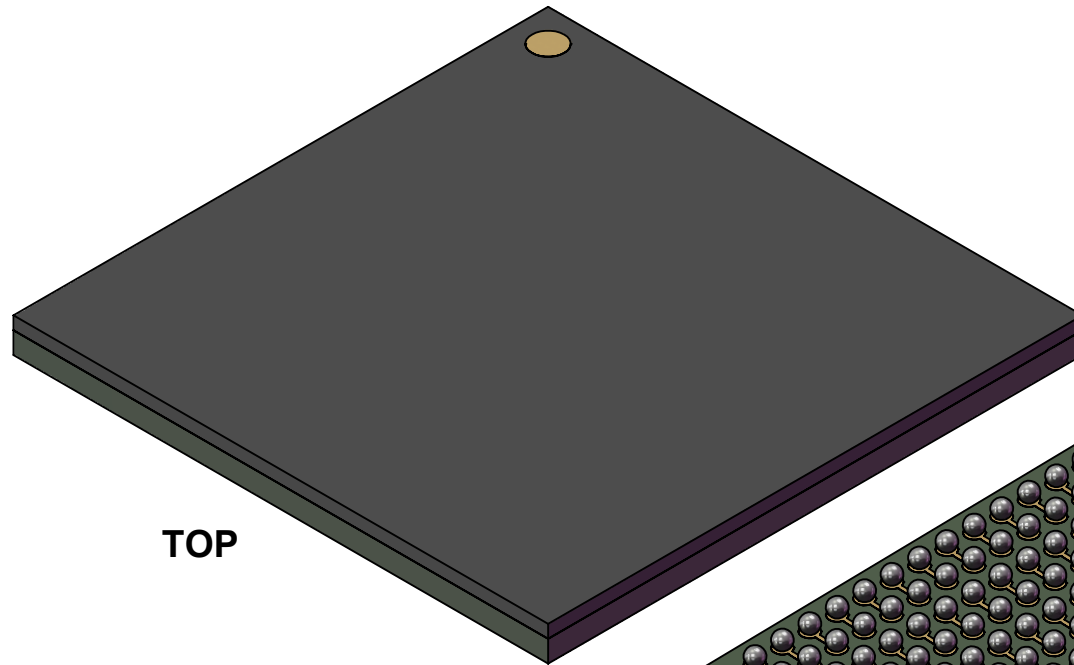
Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.76mm (30 MIL).
- 3) SMD (SOLDER MASK DEFINED) PAD OPENING: 0.61 mm (24 MIL).
- 4) PCB TRACING LINE WIDTH 0.203 mm (8 MIL).

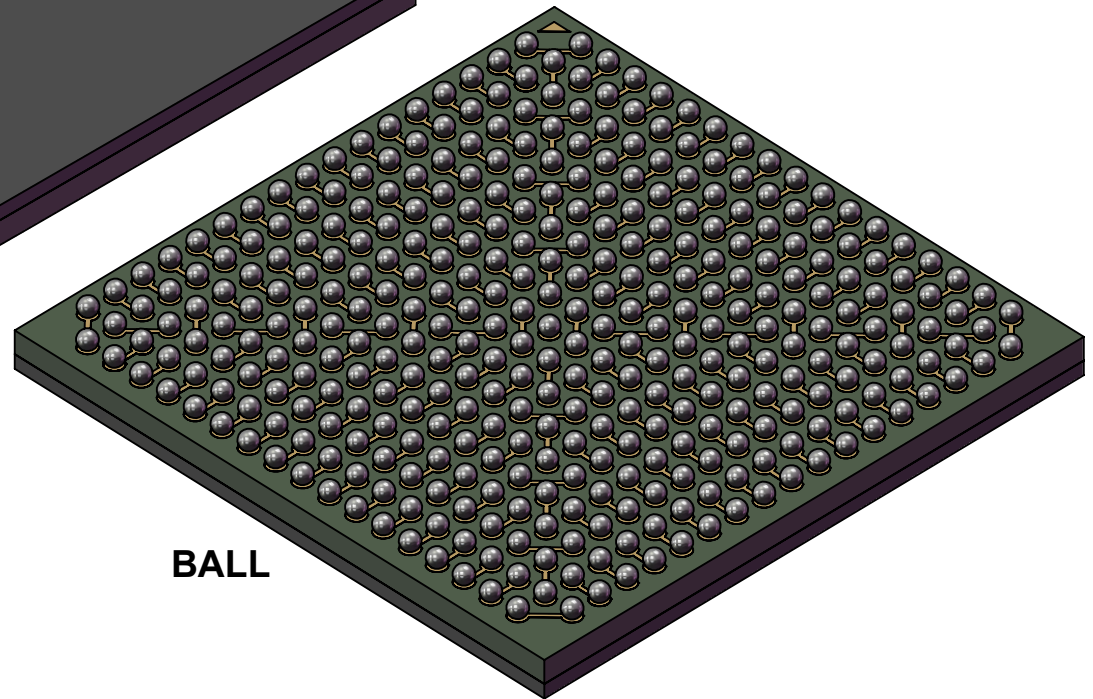
TopLine®

TITLE			
BGA357T1.27-DC73D DAISY CHAIN			
SCALE	SIZE	DRAWING NO.	REV
4:1	A	521903	A
DO NOT SCALE DRAWING			SHEET 2 OF 4

**MODEL
BGA WITH BALL**



TOP



BALL

TopLine®

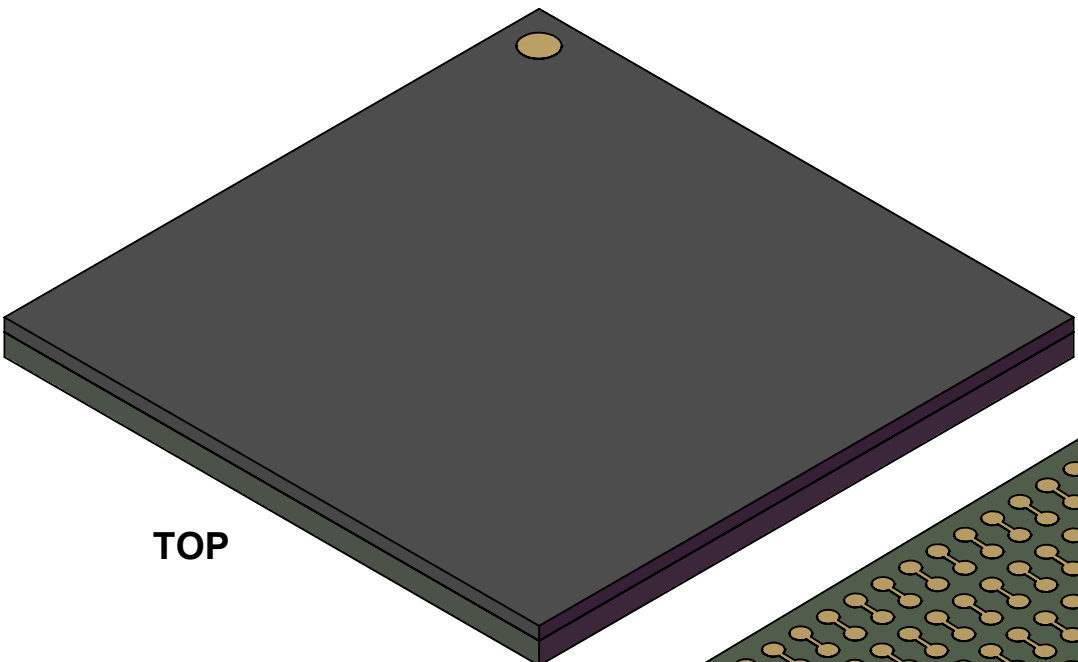
TITLE BGA357T1.27-DC73D
DAISY CHAIN

SCALE 4:1	SIZE A	DRAWING NO. 521903	REV A
--------------	-----------	-----------------------	----------

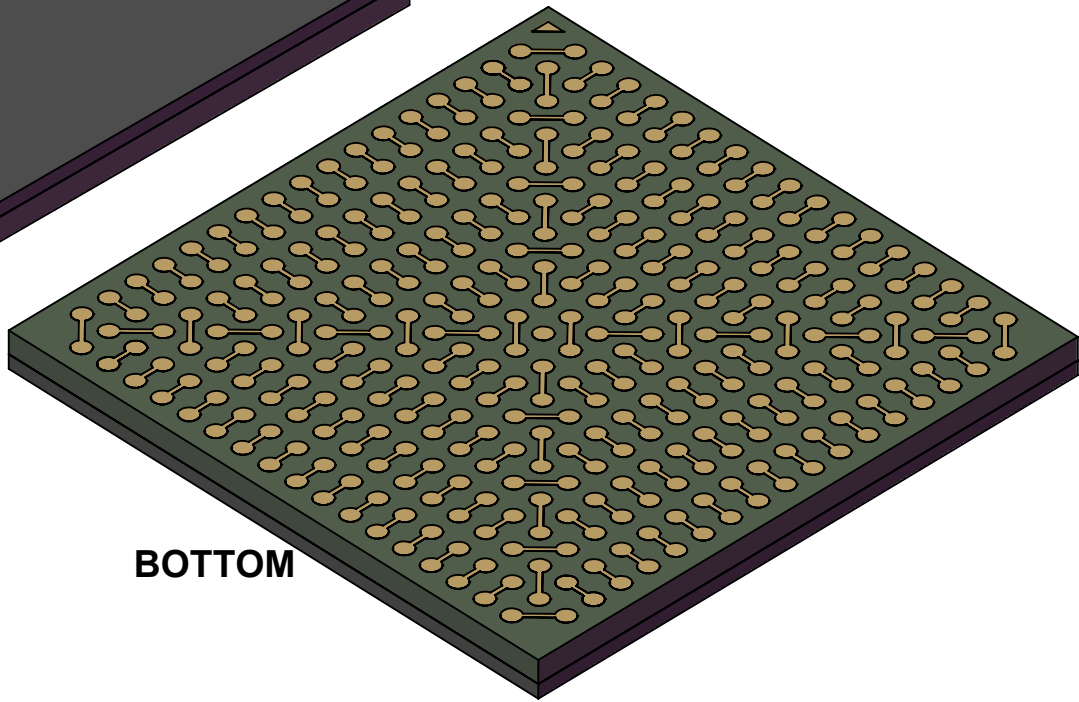
DO NOT SCALE DRAWING

SHEET 3 OF 4

**MODEL
LGA WITHOUT BALL**



TOP



BOTTOM

TopLine[®]			
TITLE		BGA357T1.27-DC73D DAISY CHAIN	
SCALE	SIZE	DRAWING NO.	REV
4:1	A	521903	A
DO NOT SCALE DRAWING			SHEET 4 OF 4